

AMPLIMITE | AMPLIMITE 0.50 Series

TE Internal #: 787928-7

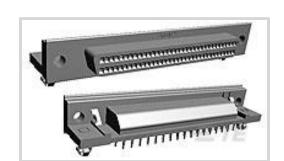
PCB D-Sub Connectors, Receptacle, Cable-to-Board, 68 Position, 1.27 mm [.05 in] Centerline, 2 Row, Standard Profile, AMPLIMITE

0.50 Series

View on TE.com >



Connectors > D-Shaped Connectors > D-Sub Connectors > PCB D-Sub Connectors > D-Sub Receptacle Assembly: Right Angle, 1.27mm



Connector & Housing Type: Receptacle

Connector System: Cable-to-Board

Number of Positions: 68

Centerline (Pitch): 1.27 mm [.05 in]

Number of Rows: 2

All D-Sub Receptacle Assembly: Right Angle, 1.27mm (76)

Features

Product Type Features

Shell Type	Full Metal Shell
Connector & Housing Type	Receptacle
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Shielded	Yes
Connector Type	Connector Assembly
Product Type	Connector
Configuration Features	
Number of Positions	68
Number of Rows	2
PCB Mount Orientation	Right Angle
Body Features	

Zinc

Standard

Nickel over Copper

Tin-Lead over Nickel

← For support call+1 800 522 6752

Bracket Material

Bracket Plating Material

Post Plating Material

Connector Profile



Contact Features Contact Mating Area Plating Material Contact Underplating Material PCB Contact Termination Area Plating Material Contact Base Material Contact Current Rating (Max) 1 Termination Features Termination Method to Printed Circuit Board Termination Post Length Mechanical Attachment PCB Mount Alignment PCB Mount Retention PCB Mount Retention Type Mating Retention Type Mating Retention Type Mating Alignment Mechanical Mating Type Mating Alignment Mating Features Centerline (Pitch) Housing Material	ickel 12 in old, Gold Flash over Palladium Nickel ickel, Palladium Nickel in-Lead hosphor Bronze A O µin hrough Hole - Solder 66 mm[.144 in]
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Housing Features Centerline (Pitch) Housing Material Housing Color Bl	/ithout
Centerline (Pitch) Housing Material Housing Color B	25 in
Housing Material Housing Color Bl	
Housing Color Bl	27 mm[.05 in]
Dimensions	hermoplastic
Row-to-Row Spacing 2.	hermoplastic
.0	hermoplastic
Usage Conditions	hermoplastic lack
Operating Temperature Range -5	hermoplastic lack 54 mm[.1 in]
Operation/Application	hermoplastic lack 54 mm[.1 in]



Circuit Application	Signal
Industry Standards	
Approved Standards	UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tube
Packaging Quantity	8

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

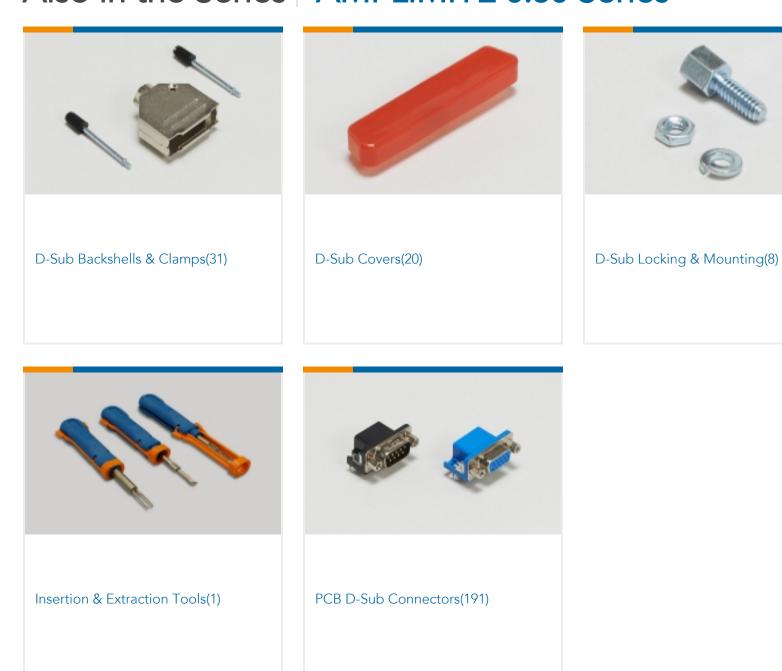
Compatible Parts



IDC D-Sub Connectors(76)



Also in the Series | AMPLIMITE 0.50 Series



Documents

Product Drawings
68 50SR R/A RECPT, REDESIGN

English

CAD Files

Customer View Model

ENG_CVM_787928-7_G.3d_igs.zip

English

Customer View Model

ENG_CVM_787928-7_G.3d_stp.zip

English

Customer View Model

ENG_CVM_787928-7_G.2d_dxf.zip

English

3D PDF

English

PCB D-Sub Connectors, Receptacle, Cable-to-Board, 68 Position, 1.27 mm [.05 in] Centerline, 2 Row, Standard Profile, AMPLIMITE 0.50 Series



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Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English

Agency Approvals

UL

English